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conductive material [is a non-conductive particulate material] comprises alumina or boron nitride or both.

3. (Amended) The electrically resistive composite material of claim [2 wherein the particulate material is selected from metal oxides, metal nitrides, ceramics, and mixtures thereof] 1 wherein the conductive material comprises copper.

A1
con'd.
4. (Amended) The electrically resistive composite material of claim [3 wherein the non-conductive particulate materials is selected from the group consisting of boron nitride, silicon carbide, alumina, silica, platinum oxide, tantalum nitride, talc, polyethylene tetra-fluoroethylene (PTFE), epoxy powders, and mixtures thereof] 1 wherein the conductive material comprises is not copper.

5. (Amended) The electrically resistive composite material of claim 1 [wherein the conductive material is a metal, metalloid, alloy, or combination thereof] which has a resistivity of from about 1 to about 10,000 ohms/square.

8. (Amended) The multi-layer foil of claim 6 [wherein the electrically resistive composite material layer non-conductive material is a non-conductive particulate material selected from metal oxides, metal nitrides, ceramics, and mixtures thereof] wherein the conductive material comprises copper.

A2
9. (Amended) The multi-layer foil of claim [8 wherein the non-conductive particulate materials is selected from the group consisting of boron nitride, silicon carbide, alumina, silica, platinum oxide, tantalum nitride, talc, polyethylene tetra-fluoroethylene (PTFE), epoxy powders, and mixtures thereof] 6 wherein the conductive material comprises is not copper.

10. (Amended) The multi-layer foil of claim 6 wherein the conductive material [is a metal, metalloid, alloy, or combination thereof] comprises nickel.

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11. (Amended) A multi-layer foil comprising a copper metal layer having a shiny surface, and an electrically resistive composite material layer associated with the copper metal layer shiny surface wherein the electrically resistive composite material layer includes from about 0.01 to about 99.9 area % of a conductive metal other than copper and from about 0.01 to about 99.9 area % of particles of a non-conductive material selected from alumina, boron nitride, and mixtures thereof.

Please add the following claims:

21. The electrically resistive composite material of claim 1 wherein the conductive material comprises nickel.

22. The electrically resistive composite material of claim 1 wherein the amount of non-conductive material in the electrically resistive composite material ranges from about 0.01 to about 99.9 area %.

23. The electrically resistive composite material of claim 1 wherein the amount of conductive material in the electrically resistive composite material ranges from about 0.01 to about 99.9 area %.

24. The multi-layer foil of claim 6 wherein the conductive metal layer comprises copper.

25. The multi-layer foil of claim 6 wherein the conductive metal layer comprises copper and the conductive material does not comprise copper.

26. The multi-layer foil of claim 6 wherein the conductive metal layer comprises copper and the conductive material comprises nickel.